

## POTTING CRACK SHIELD AND RELATED METHOD

## ABSTRACT OF THE DISCLOSURE

An electronic component includes a circuit board assembly having a thin polymer sheet having no electronic function located within the assembly, the circuit board assembly and the thin polymer sheet encapsulated in a potting material. A method of preventing damage to circuit boards in an electronic component encapsulated in potting material due to cracks in the potting material includes a) providing plural circuit boards for assembly into the component; b) during assembly, inserting a thin polymer film at least between adjacent ones of the plural circuit boards, said polymer film having no electronic function; c) completing the assembly of the component; and d) encapsulating the component in a potting material.